

MMVL3401T1

Preferred Device

Silicon Pin Diode

This device is designed primarily for VHF band switching applications but is also suitable for use in general-purpose switching circuits. Supplied in a Surface Mount package.

- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Capacitance — 0.7 pF Typ at $V_R = 20$ Vdc
- Very Low Series Resistance at 100 MHz — 0.34 Ohms (Typ) @ $I_F = 10$ mAdc
- Device Marking: 4D

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V_R	Continuous Reverse Voltage	20	Vdc
I_F	Peak Forward Current	20	mAdc

THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
P_D	Total Device Dissipation FR-5 Board,*	200	mW
	$T_A = 25^\circ\text{C}$ Derate above 25°C	1.57	mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	635	$^\circ\text{C}/\text{W}$
T_J, T_{stg}	Junction and Storage Temperature	150	$^\circ\text{C}$

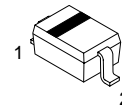
*FR-4 Minimum Pad



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SILICON PIN SWITCHING DIODE



PLASTIC
SOD-323
CASE 477



ORDERING INFORMATION

Device	Package	Shipping
MMVL3401T1	SOD-323	3000 / Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

MMVL3401T1

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \mu\text{A}$)	$V_{(BR)R}$	35	—	—	Vdc
Diode Capacitance ($V_R = 20 \text{Vdc}$)	C_T	—	—	1.0	pF
Series Resistance (Figure 5) ($I_F = 10 \text{mA}$, $f = 100 \text{MHz}$)	R_S	—	—	0.7	Ω
Reverse Leakage Current ($V_R = 25 \text{Vdc}$)	I_R	—	—	0.1	μA

TYPICAL CHARACTERISTICS

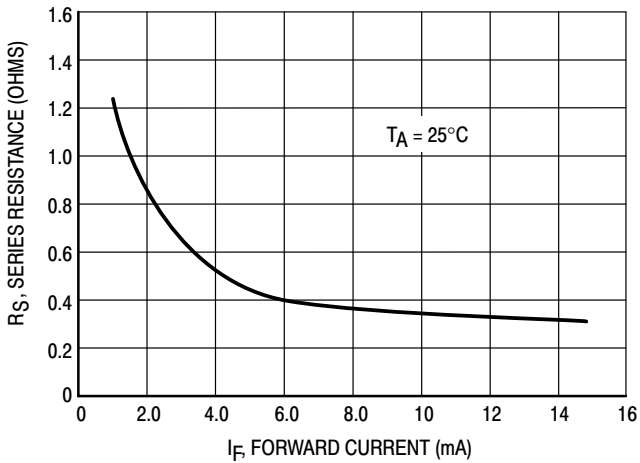


Figure 1. Series Resistance

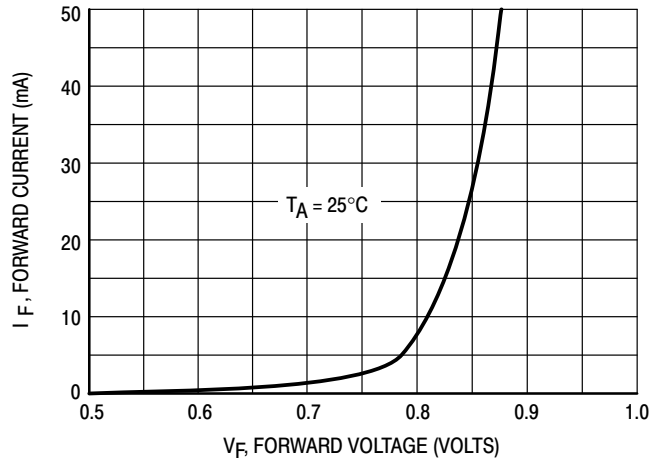


Figure 2. Forward Voltage

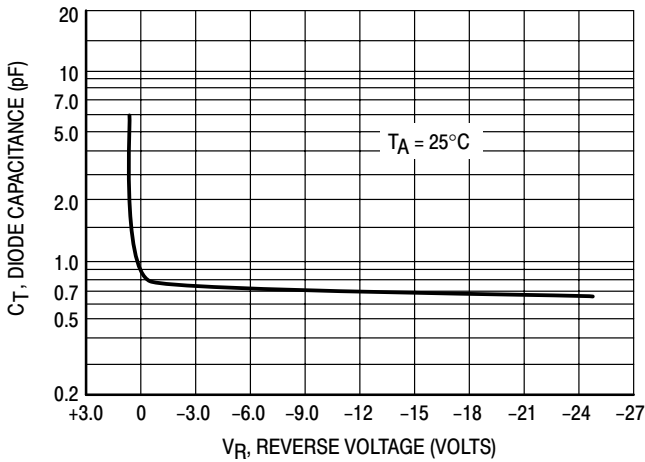


Figure 3. Diode Capacitance

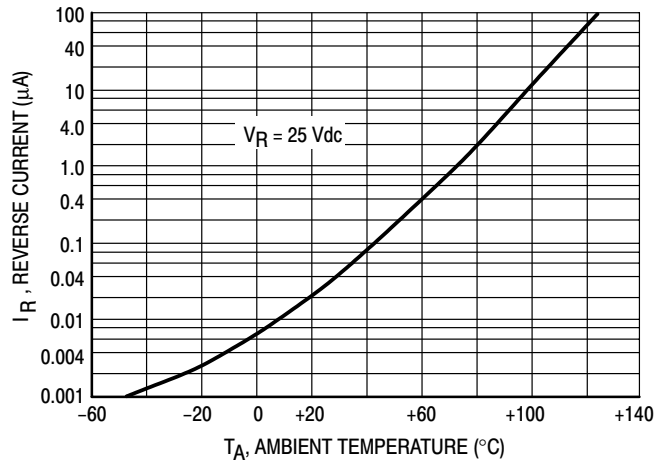
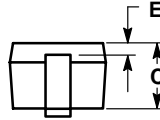
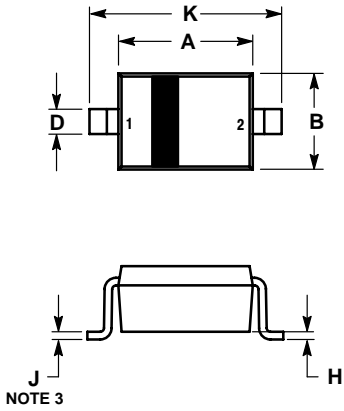


Figure 4. Leakage Current

MMVL3401T1

PACKAGE DIMENSIONS

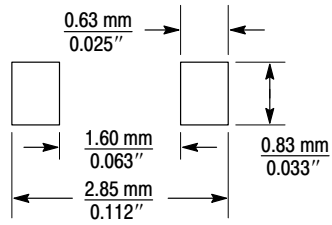
SOD-323
 PLASTIC PACKAGE
 CASE 477-02
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.60	1.80	0.063	0.071
B	1.15	1.35	0.045	0.053
C	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
E	0.15 REF		0.006 REF	
H	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.70	0.091	0.106


STYLE 1:
 PIN 1. CATHODE
 2. ANODE



($\frac{\text{mm}}{\text{inches}}$)

SOD-323
 Soldering Footprint

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